

FEATURES

- ESD Protection for RS-232 Bus Pins
 - ± 15 -kV Human-Body Model (HBM)
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates at 5-V V_{CC} Supply
- Four Drivers and Five Receivers
- Operates up to 120 kbit/s
- Low Supply Current in Shutdown Mode . . . 15 μ A Typ
- External Capacitors . . . 4×0.1 F
- Designed to Be Interchangeable With Industry Standard '213 Devices
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II

APPLICATIONS

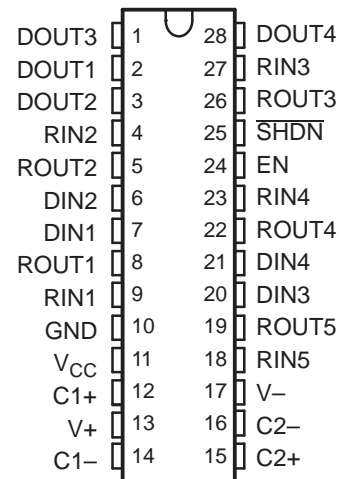
- Battery-Powered Systems
- PDAs
- Notebooks
- Laptops
- Palmtop PCs
- Hand-Held Equipment

DESCRIPTION/ ORDER INFORMATION

The TRS213 device consists of four line drivers, five line receivers, and a dual charge-pump circuit with ± 15 -kV ESD protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 5-V supply. The devices operate at data signaling rates up to 120 kbit/s and a maximum of 30-V/ μ s driver output slew rate.

The TRS213 has an active-low shutdown ($\overline{\text{SHDN}}$) and an active-high enable control (EN). In shutdown mode, the charge pumps are turned off, V+ is pulled down to V_{CC} , V– is pulled to GND, and the transmitter outputs are disabled. This reduces supply current typically to 1 μ A. Two receivers of the TRS213 are active during shutdown.

DB, DW, OR PW PACKAGE
(TOP VIEW)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TRS213
5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER
WITH ± 15 -kV ESD PROTECTION

SLLS807–JUNE 2007

ORDERING INFORMATION

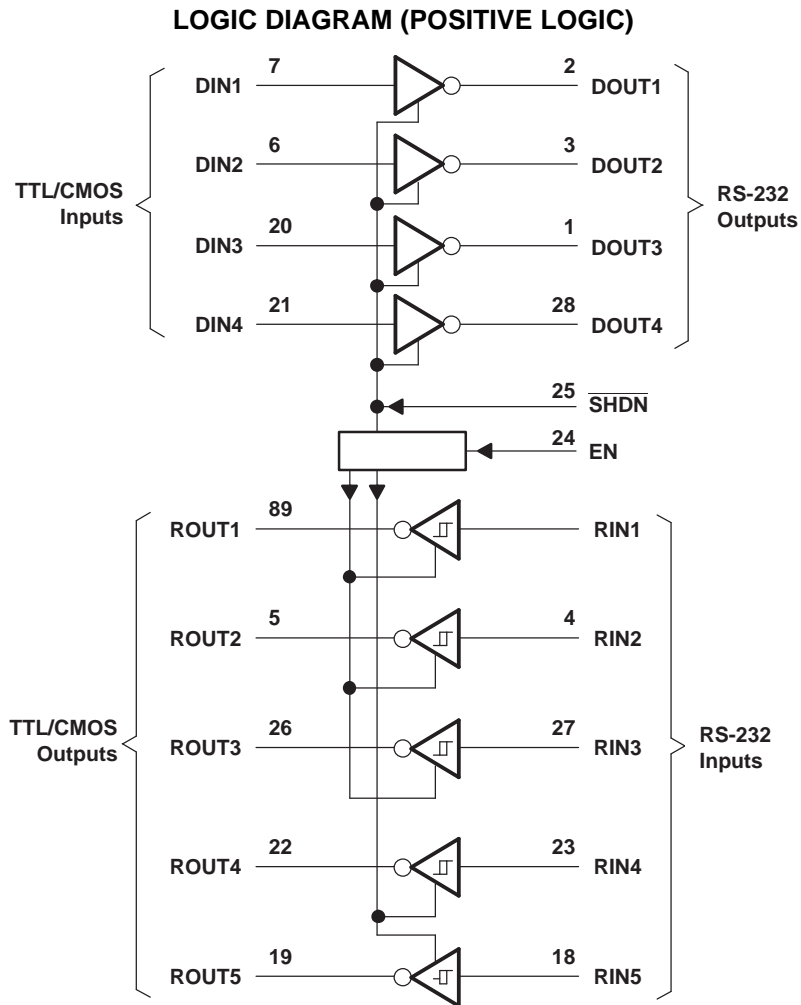
T _A	PACKAGE ⁽¹⁾⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	SOIC – DW	Tube of 20	TRS213CDW	TRS213C
		Reel of 1000	TRS213CDWR	
	SSOP – DB	Tube of 50	TRS213CDB	TRS213C
		Reel of 2000	TRS213CDBR	
	TSSOP – PW	Tape and reel	TRS213CPWR	TRS213C
	–40°C to 85°C	SOIC – DW	Tube of 20	TRS213IDW
Reel of 1000			TRS213IDWR	
SSOP – DB		Tube of 50	TRS213IDB	TRS213I
		Reel of 2000	TRS213IDBR	
TSSOP – PW		Tape and reel	TRS213IPWR	TRS213I

- (1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.
- (2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

FUNCTION TABLE

INPUTS		DRIVER D1–D4	RECEIVER		DEVICE STATUS
$\overline{\text{SHDN}}$	EN		R1–R3	R4–R5	
L	L	Z	Z	Z	Shutdown
L	H	Z	Z	Active ⁽¹⁾	Shutdown
H	L	All active	Z	Z	Normal operation
H	H	All active	Active	Active	Normal operation

- (1) See the V_{IT+} and V_{IT–} change in the Electrical Characteristics table.



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5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER WITH ± 15 -kV ESD PROTECTION

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Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V _{CC}	Supply voltage range	−0.3	6	V
V+	Positive charge-pump voltage range ⁽²⁾	V _{CC} − 0.3	14	V
V−	Negative charge-pump voltage range ⁽²⁾	0.3	−14	V
V _I	Input voltage range	Drivers	V+ + 0.3	V
		Receivers	±30	
V _O	Output voltage range	Drivers	V− − 0.3	V
		Receivers	−0.3	
DOUT	Short-circuit duration	Continuous		
θ _{JA}	Package thermal impedance ⁽³⁾⁽⁴⁾	DB package	62	C°/W
		DW package	46	
		PW package		
T _J	Operating virtual junction temperature		150	C°
T _{stg}	Storage temperature range	−65	150	C°

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to network GND.
- (3) Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_J(max) − T_A)/θ_{JA}. Operating at the absolute maximum T_J of 150°C can affect reliability.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

See [Figure 4](#)

		MIN	NOM	MAX	UNIT
Supply voltage		4.5	5	5.5	V
V _{IH}	Driver high-level input voltage	2			V
	Control high-level input voltage	2.4			
V _{IL}	Driver and control low-level input voltage			0.8	V
V _I	Driver and control input voltage	0		5.5	V
	Receiver input voltage	−30		30	
T _A	Operating free-air temperature	TRS213C	0	70	°C
		TRS213I	−40	85	

- (1) Test conditions are C1–C4 = 0.1 μF at V_{CC} = 5 V ± 0.5 V.

Electrical Characteristics⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
I _{CC}	Supply current No load, See Figure 6		14	20	mA
I _{SHDN}	Shutdown supply current T _A = 25°C, See Figure 1		15	50	μA

- (1) Test conditions are C1–C4 = 0.1 μF at V_{CC} = 5 V ± 0.5 V.
- (2) All typical values are at V_{CC} = 5 V, and T_A = 25°C.

DRIVER SECTION

Electrical Characteristics⁽¹⁾

over operating free-air temperature range (unless otherwise noted) (see Figure 4)

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
V _{OH}	High-level output voltage	DOUT at R _L = 3 k Ω to GND	5	9		V
V _{OL}	Low-level output voltage	DOUT at R _L = 3 k Ω to GND	–5	–9		V
I _{IH}	Control high-level input current	EN, $\overline{\text{SHDN}}$ = 5 V		3	10	μ A
I _{IL}	Driver low-level input current	DIN = 0 V		–15	–200	μ A
	Control low-level input current	EN, $\overline{\text{SHDN}}$ = 0 V		–3	–10	
I _{OS} ⁽³⁾	Short-circuit output current	V _{CC} = 5.5 V, V _O = 0 V		± 10	± 60	mA
r _o	Output resistance	V _{CC} , V+, and V– = 0 V, V _O = ± 2 V	300			Ω

(1) Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 5 V \pm 0.5 V

(2) All typical values are at V_{CC} = 5 V, and T_A = 25°C.

(3) Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

Switching Characteristics⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
	Maximum data rate	C _L = 50 pF to 1000 pF, One DO _{UT} switching, R _L = 3 k Ω to 7 k Ω , See Figure 3	120			kbit/s
t _{PLH(D)}	Propagation delay time, low- to high-level output	C _L = 2500 pF, All drivers loaded, R _L = 3 k Ω , See Figure 3		2		μ s
t _{PHL(D)}	Propagation delay time, high- to low-level output	C _L = 2500 pF, All drivers loaded, R _L = 3 k Ω , See Figure 3		2		μ s
t _{sk(p)}	Pulse skew ⁽³⁾	C _L = 150 pF to 2500 pF, See Figure 3, R _L = 3 k Ω to 7 k Ω		300		ns
SR(tr)	Slew rate, transition region (see Figure 2)	C _L = 50 pF to 1000 pF, V _{CC} = 5 V, R _L = 3 k Ω to 7 k Ω	3	6	30	V/ μ s

(1) Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 5 V \pm 0.5 V.

(2) All typical values are at V_{CC} = 5 V, and T_A = 25°C.

(3) Pulse skew is defined as (t_{PLH} – t_{PHL}) of each channel of the same device.

ESD Protection

over operating free-air temperature range (unless otherwise noted)

PIN	TEST CONDITIONS	TYP	UNIT
DO _{UT}	Human-Body Model	± 15	kV

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5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER WITH ± 15 -kV ESD PROTECTION

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RECEIVER SECTION

Electrical Characteristics⁽¹⁾

over operating free-air temperature range (unless otherwise noted) (see [Figure 6](#))

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽²⁾	MAX	UNIT
V _{OH}	High-level output voltage	I _{OH} = -1 mA		V _{CC} - 0.4			V
V _{OL}	Low-level output voltage	I _{OH} = 1.6 mA		0.4			V
V _{IT+}	Positive-going input threshold voltage	V _{CC} = 5 V, T _A = 25°C	Active mode	1.7		2.4	V
			Shutdown mode (R4–R5)	1.5		2.4	
V _{IT-}	Negative-going input threshold voltage	V _{CC} = 5 V, T _A = 25°C	Active mode	0.8	1.2		V
			Shutdown mode (R4–R5)	0.6	1.5		
V _{hys} ⁽³⁾	Input hysteresis (V _{IT+} , V _{IT-})	V _{CC} = 5 V		0.5		1	V
r _I	Input resistance	V _{CC} = 5 V, T _A = 25°C		3	5	7	kΩ
Output leakage current		EN = 0 V, 0 ≤ ROUT ≤ V _{CC} , R1–R3		±0.05		±10	μA

(1) Test conditions are C1–C4 = 0.1 μF at V_{CC} = 5 V ± 0.5 V.

(2) All typical values are at V_{CC} = 5 V, and T_A = 25°C.

(3) No hysteresis in shutdown mode

Switching Characteristics⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽²⁾	MAX	UNIT
t _{PLH(R)}	Propagation delay time, low- to high-level output	C _L = 150 pF, See Figure 4	SHDN = V _{CC}	0.5	10		μs
			SHDN = 0 V, R4–R5	4		40	
t _{PHL(R)}	Propagation delay time, high- to low-level output	C _L = 150 pF, See Figure 4		0.5	10		μs
t _{en}	Output enable time	C _L = 150 pF, See Figure 5		600			ns
t _{dis}	Output disable time	C _L = 150 pF, See Figure 5		200			ns

(1) Test conditions are C1–C4 = 0.1 μF at V_{CC} = 5 V ± 0.5 V.

(2) All typical values are at V_{CC} = 5 V, and T_A = 25°C.

ESD Protection

over operating free-air temperature range (unless otherwise noted)

PIN	TEST CONDITIONS	TYP	UNIT
RIN	Human-Body Model	±15	kV

PARAMETER MEASUREMENT INFORMATION

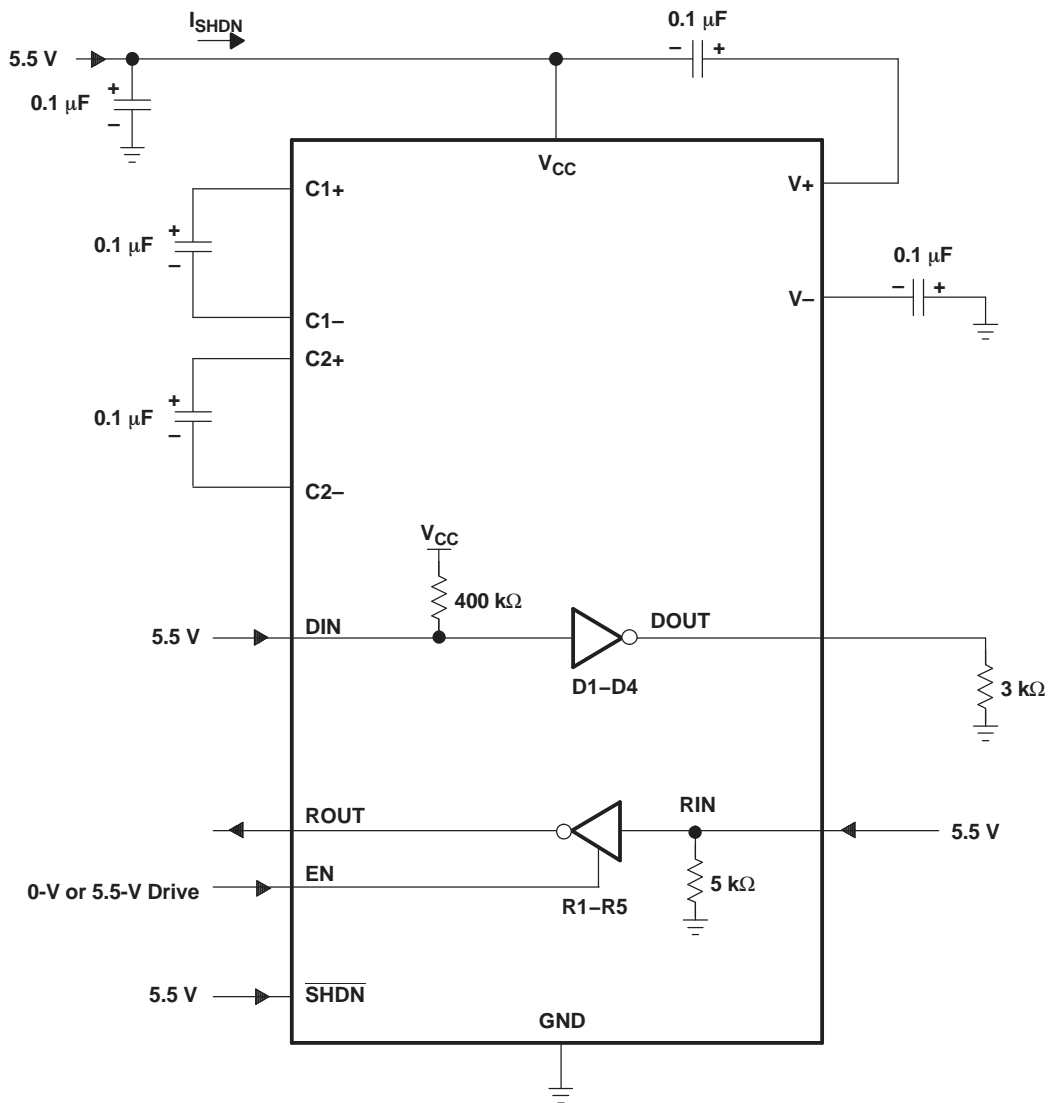
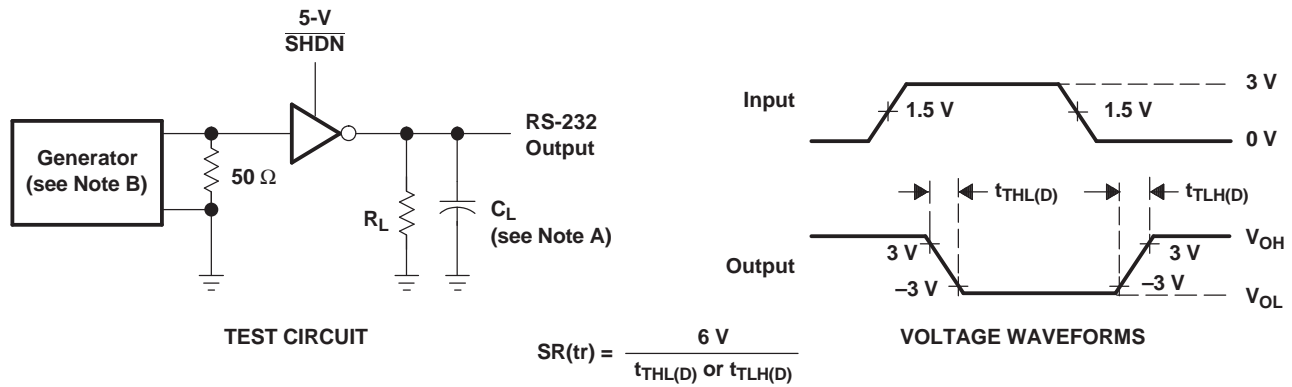
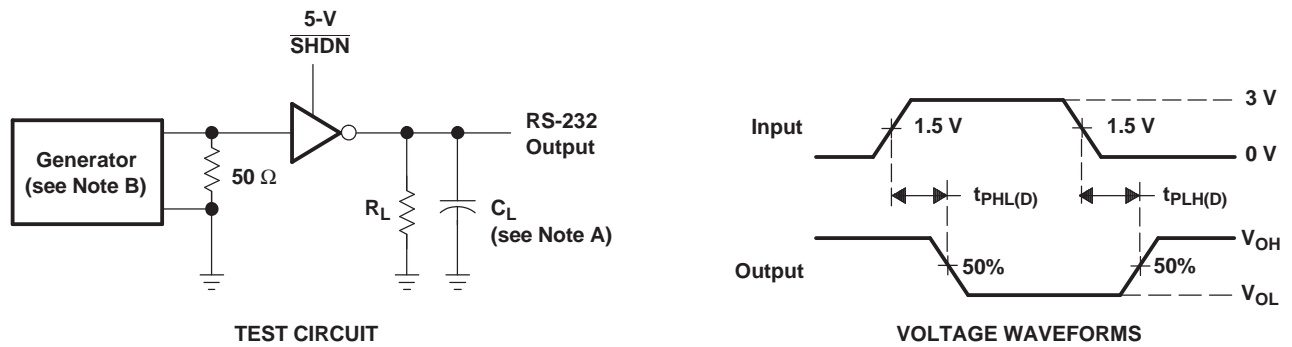


Figure 1. Shutdown Current Test Circuit



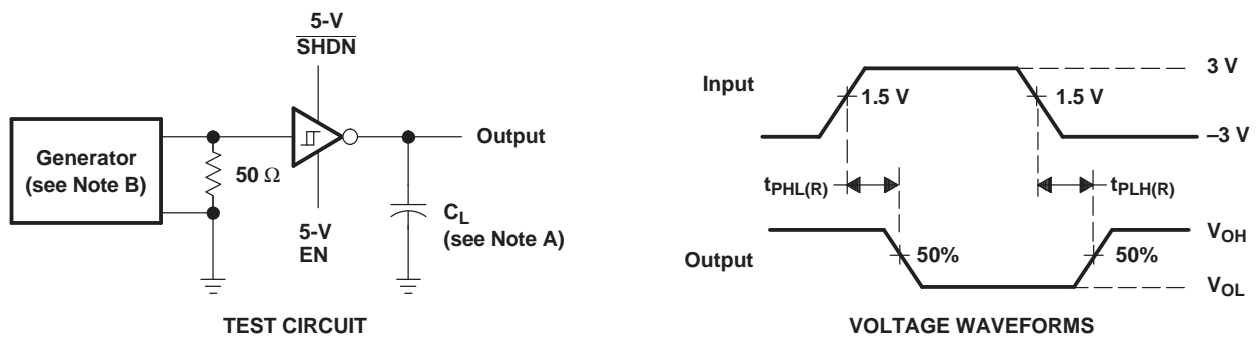
NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.

Figure 2. Driver Slew Rate



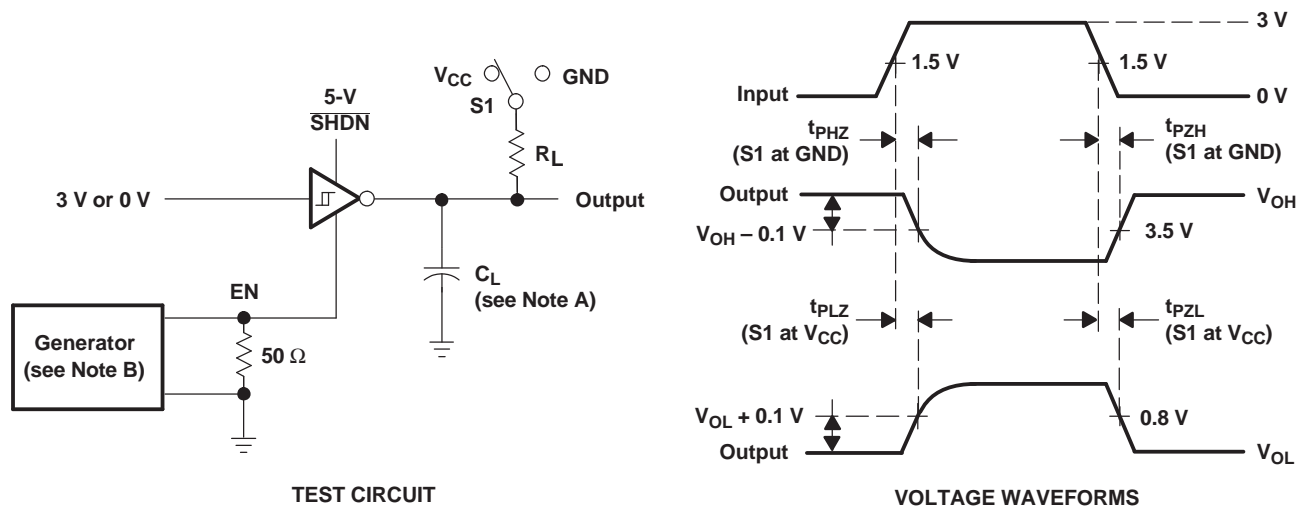
NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.

Figure 3. Driver Pulse Skew and Propagation Delay Times



NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.

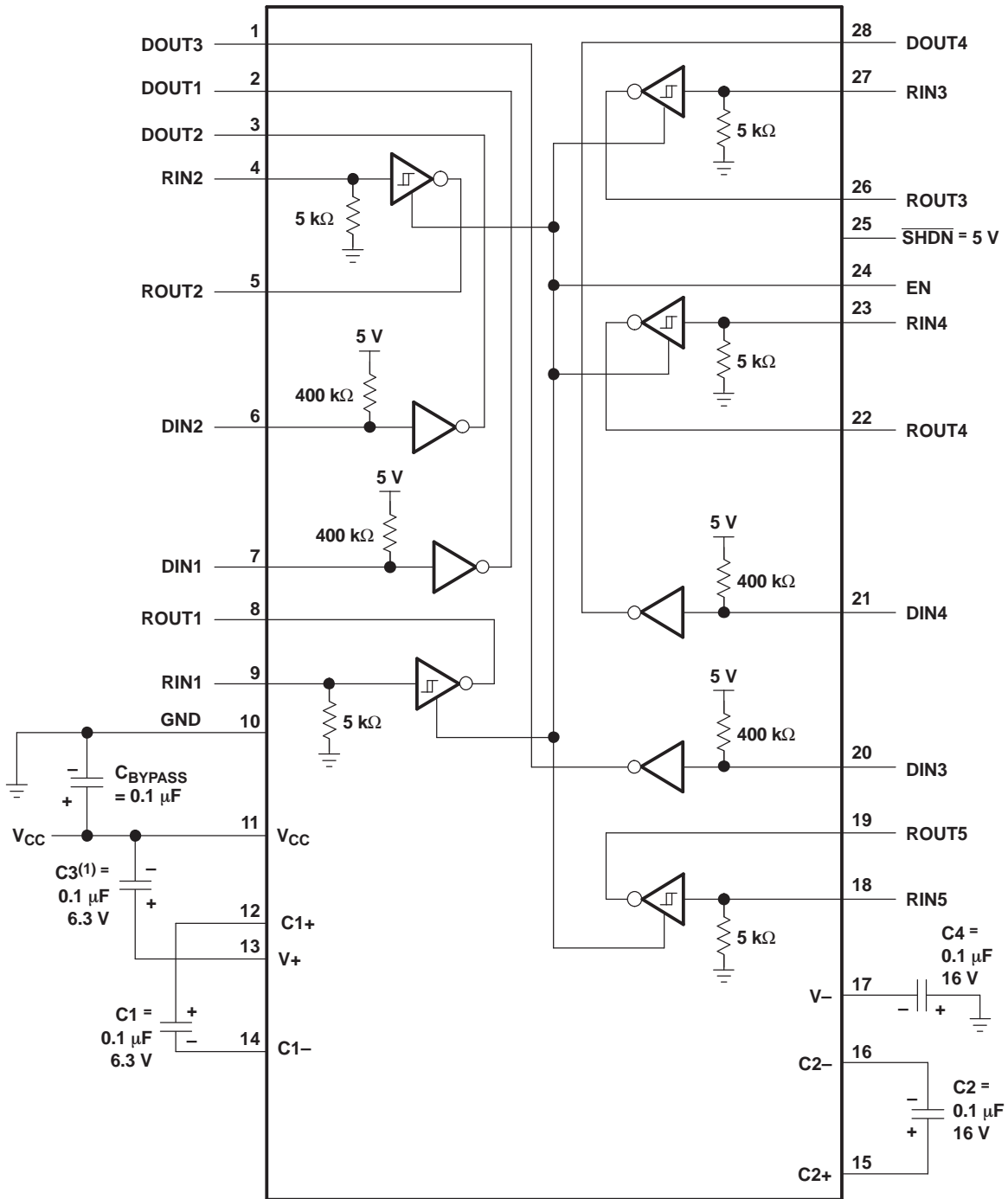
Figure 4. Receiver Propagation Delay Times



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_r \leq 10$ ns, $t_f \leq 10$ ns.
 - C. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - D. t_{PZL} and t_{PZH} are the same as t_{en} .

Figure 5. Receiver Enable and Disable Times

APPLICATION INFORMATION



(1) C3 can be connected to V_{CC} or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

Figure 6. Typical Operating Circuit and Capacitor Values

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TRS213CDBR	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TRS213C	Samples
TRS213IDB	ACTIVE	SSOP	DB	28	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TRS213I	Samples
TRS213IDBR	ACTIVE	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TRS213I	Samples
TRS213IDWR	ACTIVE	SOIC	DW	28	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	TRS213I	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TRS213CDBR	SSOP	DB	28	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
TRS213IDBR	SSOP	DB	28	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
TRS213IDWR	SOIC	DW	28	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS

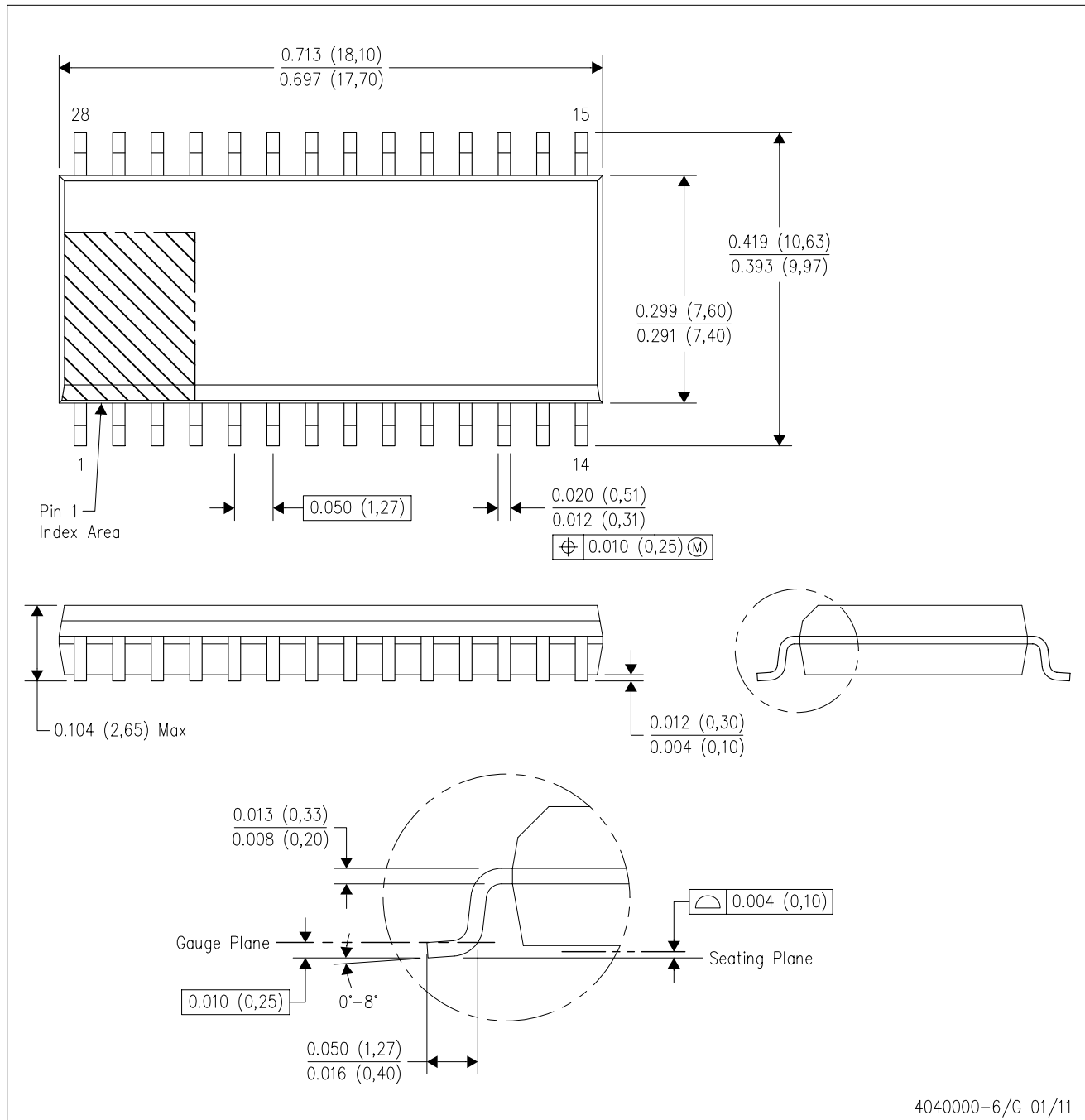


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TRS213CDBR	SSOP	DB	28	2000	367.0	367.0	38.0
TRS213IDBR	SSOP	DB	28	2000	367.0	367.0	38.0
TRS213IDWR	SOIC	DW	28	1000	350.0	350.0	66.0

DW (R-PDSO-G28)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AE.

DB0028A



PACKAGE OUTLINE

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



4214853/B 03/2018

NOTES:

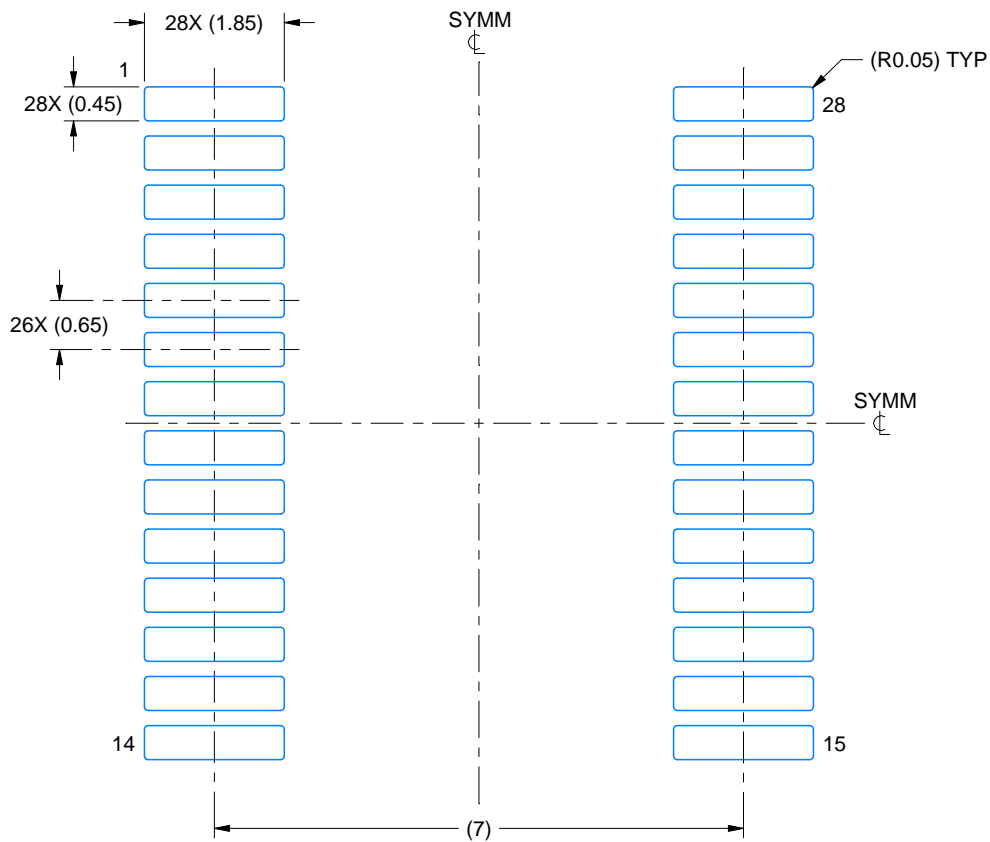
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

DB0028A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4214853/B 03/2018

NOTES: (continued)

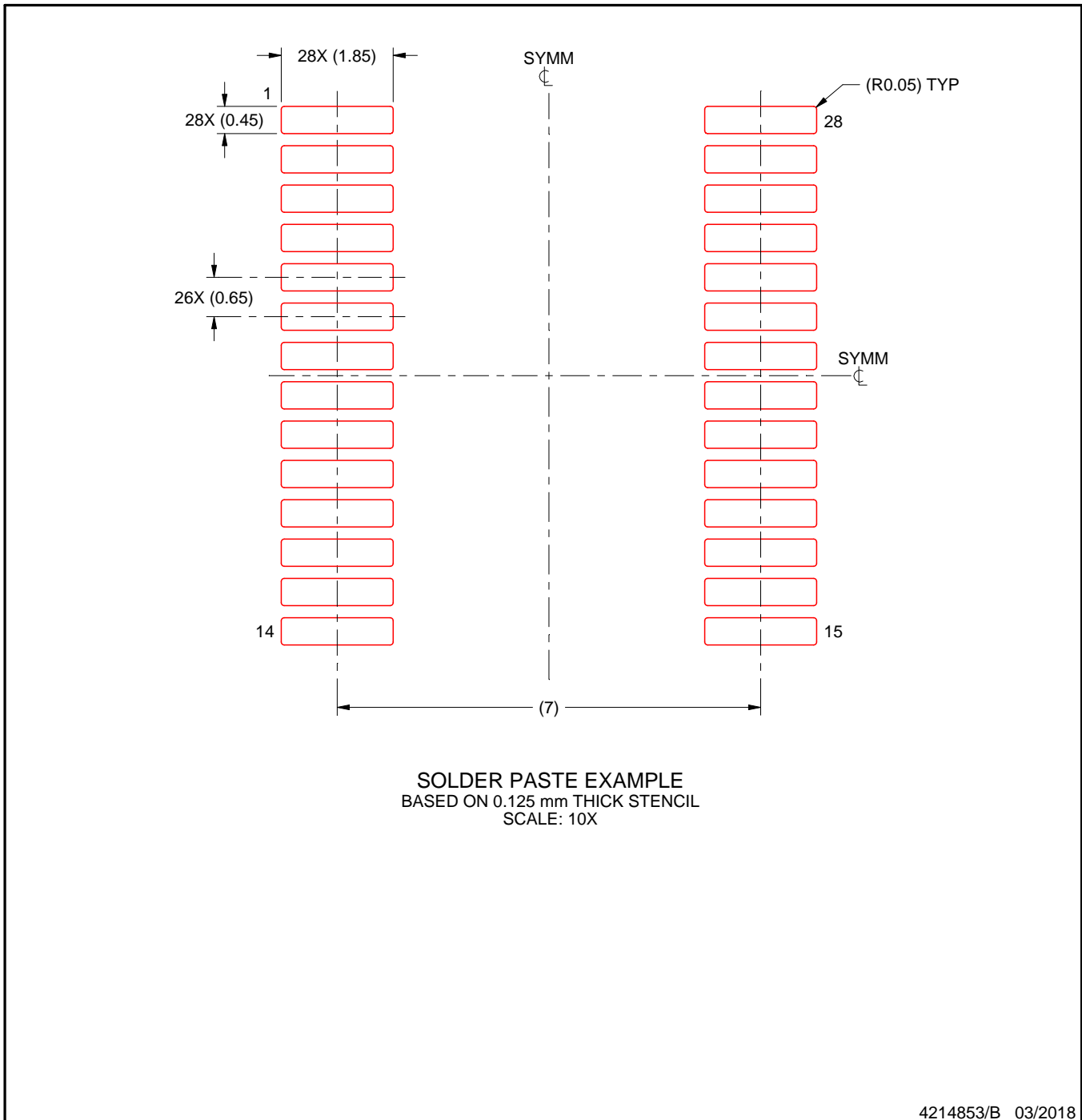
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0028A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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